

CHEMTRONICS[®]

Technical Data Sheet

TDS # SWick

Soder-Wick[®] Desoldering Braid

PRODUCT DESCRIPTION

Soder-Wick[®] offers the state of the art in desoldering technology. Soder-Wick[®] is designed for today's heat sensitive electronic components using lighter mass, pure copper braid construction that allows for better thermal conductivity, even at low temperatures. Soder-Wick[®] responds faster than conventional desoldering braids thereby minimizing overheating and preventing PCB damage. A full range of sizes and flux types are available, including Rosin, No Clean, unfluxed and a high temperature Lead-Free version. Whatever the requirement, Soder-Wick[®] has the answer.

- Requires little or no post solder cleaning
- No corrosive residues
- Optimized construction for faster wicking and heat transfer
- Halide free
- Minimizes the risk of heat damage to components and circuit boards

TYPICAL APPLICATIONS

Soder-Wick[®] desoldering braid safely removes solder from:

- Thru-hole Components
- SMT Pads and BGA Pads
- Micro Circuits
- Terminals
- Lugs and Posts
- Identification Script

TYPICAL PRODUCT DATA AND PHYSICAL PROPERTIES

Flux Types:	Rosin Grade WW, Type "R" Patented No Clean High Temperature No Clean		
Specifications:	ANSI/IPC J STD-004 MIL-F-14256 F		
No Clean Flux Spec:	MIL-STD-883B Bellcore TR-NWT-000078 ANSI/IPC J SF818		
Shelflife:	2 years		
RoHS/WEEE Status			
	Width Inches	Color	Width Metric
Size #			
1	.030"	White	0.8mm
2	.060"	Yellow	1.5mm
3	.080"	Green	2.0mm
4	.110"	Blue	2.8mm
5	.145"	Brown	3.7mm
6	.210"	Red	5.3mm
BGA	-	Purple	-

STATIC DISSIPATIVE PACKAGING

Soder-Wick[®] SD is packaged on Static Dissipative bobbins in 5 and 10-foot lengths to minimize the risk of damage associated with static electricity. The static dissipative bobbins qualify as electrostatic discharge protective per MIL-STD-1686C and MIL-HDBK-263B, and meet the static delay rate provision of MIL-B-81705C.

USAGE INSTRUCTIONS

For industrial use only.

Read MSDS carefully prior to use.

- 1) Choose a Soder-Wick® desoldering braid width equal to or slightly larger than the pad or connection.
- 2) Choose a solder iron tip equal to or slightly larger than the pad or connection.
- 3) Set temperature of iron between 600-750°F
- 4) Place wick on solder joint and place tip of hot iron on top of wick
- 5) As solder becomes molten, the color of the wick will change from copper to silver.
- 6) Remove wick and iron from solder joint simultaneously once color change has stopped.
- 7) The component lead / pad is now clean and free from solder.
- 8) Clip and discard the used portion of the wick.
- 9) If needed, clean PCB with CircuitWorks® Flux Remover Pen and remove soils with a ControlWipes™ absorbent wipe.

SODER-WICK® IS DESIGNED TO MEET OR EXCEED THE FOLLOWING:

MIL-F-14256F, Type R
NASA-STD-8739.3
DOD-STD-883E, Method 2022
ANSI/IPC J STD-004, Type ROL0
BELLCORE TR-NWT-000078
ANSI/IPC J SF-818

SODER-WICK® SD BOBBINS ARE DESIGNED TO MEET OR EXCEED:

MIL-STD-2000A
MIL-B-81705C
MIL-STD-1686C
MIL-HDBK-263B

TECHNICAL & APPLICATION ASSISTANCE

Chemtronics® provides a technical hotline to answer your technical and application related questions. The toll free number is: **1-800-TECH-401.**

AVAILABILITY

Series:

- 40 Soder-Wick® Lead-Free, SD Bobbin
- 50 Soder-Wick® Rosin
- 80 Soder-Wick® Rosin, SD Bobbin
- 60 Soder-Wick® No Clean, SD Bobbin
- 70 Soder-Wick® Unfluxed
- 75 Soder-Wick® Unfluxed, SD Bobbin

VacuPak™ Packaging

The VacuPak Can contains ten five-foot bobbins in a vacuum sealed can. This package provides the highest level of cleanliness and freshness. Great for tool kit storage.

HELPFUL HINTS:

Water Soluble Users: Use Soder-Wick® Unfluxed **70** or **75** Series to dip in water soluble flux and then desolder normally.

Ball Grid Array: Use Soder-Wick® BGA with a large tipped iron to remove solder from a number of BGA pads all at once.

NOTE: This information is believed to be accurate. It is intended for professional end users having the skills to evaluate and use the data properly. ITW CHEMTRONICS® does not guarantee the accuracy of the data and assumes no liability in connection with damages incurred while using it.

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В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

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